

Abstract of the Disclosure:

A semiconductor device in chip format having a chip which has at least one first insulating layer and electrical connection pads free of the insulating layer is described. On the first insulating layer, interconnects run from the electrical connection pads to base regions of external connection elements. A further applied insulating layer is provided with openings leading from the outside to the base regions of the external connection elements. In the openings there is a conductive adhesive, onto which small balls which are metallic at least on the outside are placed. The semiconductor element can also contain a solder paste instead of a conductive adhesive in the openings, and metallized small plastic balls are placed onto the solder paste. The invention furthermore relates to methods for producing the semiconductor device described.

REL/tk